

ABSTRACT OF THE DISCLOSURE

The invention relates to an encapsulation for an organic electronics component, particularly an OLED, which can be produced by simple coating methods or printing methods and which still has a high degree of tightness with regard to environmental influences that are detrimental to the organic electronics component. This is made possible by the use of so-called fusible alloys, i.e., low-melting point metallic alloys that combine a low melting point with a high tightness from moisture and oxidizing gases.